

設計驗證
工程課
2025 -07- 08
發行
鈺緯科技開發股份有限公司

ISO9001 & ISO14001 & TS16949 **CHILISIN ELECTRONICS CORP.**

RoHS & Halogen Free & REACH Compliance.

SPECIFICATION FOR APPROVAL

Customer : 佳世達

Customer P/N: Qisda: 6H.60160.0NE DIVA: 3LFBC00701Y (L0206)

Drawing No : CE1-830744

Quantity : 0 Pcs. **Date :** 2018/03/21

Chilisin P/N : PBY201209T-601Y-N

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SPECIFICATION ACCEPTED BY:	
COMPONENT ENGINEER	
ELECTRICAL ENGINEER	
MECHANICAL ENGINEER	
APPROVED	
REJECTED	

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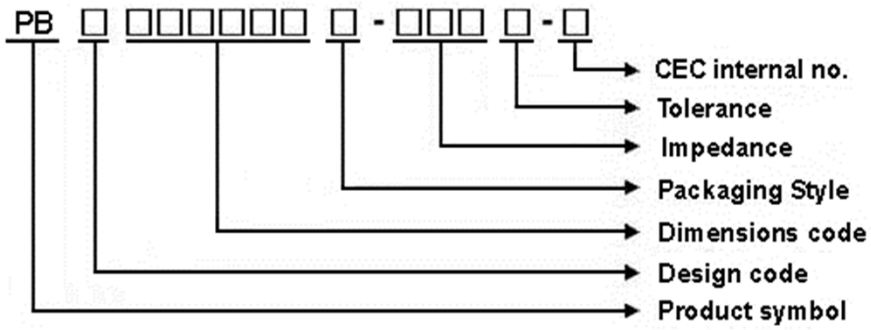
Drawn by	Checked by	Approved by
賴碧玉 **hebe.lai**	邱明傑 **Joseph.Chiu**	鍾瑞民 **jacky.chung**

ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

PBY201209T Series Specification

1 Scope: This specification applies to MULTILAYER FERRITE CHIP BEADS

2 Part Numbering:



3 Rating:

Operating Temperature: －５５℃～１２５℃(Including self - temperature rise)

Storage Temperature: －５５℃～１２５℃(after PCB)
－５℃～４０℃,Humidity ４０%～７０%(before PCB)

Packaged Storage Temperature: －10℃～４０℃,Humidity ４０%～７０%

4 Marking:

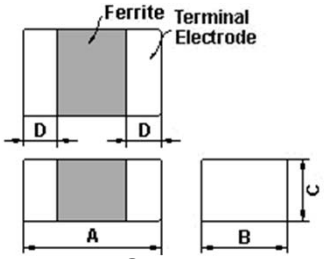
No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35℃)	20 to 30℃
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

PBY201209T Series Specification

6 Configuration and Dimensions:



Dimensions in mm

TYPE	PB201209
A	2.00±0.20
B	1.25±0.20
C	0.90±0.20
D	0.50±0.30

7 Electrical Characteristics:

Part No.	Impedance (Ω)	Test Freq.	RDC (Ω)Max.	Rated Current (mA)Max.
PBY201209T-100□-N	10	100 MHz,200 mV	0.01	6000
PBY201209T-110□-N	11	100 MHz,200 mV	0.01	6000
PBY201209T-170□-N	17	100 MHz,200 mV	0.02	5000
PBY201209T-300□-N	30	100 MHz,200 mV	0.015	4000
PBY201209T-500□-N	50	100 MHz,200 mV	0.025	3000
PBY201209T-600□-N	60	100 MHz,200 mV	0.03	3000
PBY201209T-700□-N	70	100 MHz,200 mV	0.04	3000
PBY201209T-800□-N	80	100 MHz,200 mV	0.04	3000
PBY201209T-101□-N	100	100 MHz,200 mV	0.04	3000
PBY201209T-121□-N	120	100 MHz,200 mV	0.04	3000
PBY201209T-221□-N	220	100 MHz,200 mV	0.08	2000
PBY201209T-301□-N	300	100 MHz,200 mV	0.08	2000
PBY201209T-331□-N	330	100 MHz,200 mV	0.08	2000
PBY201209T-471□-N	470	100 MHz,200 mV	0.1	2000
✓PBY201209T-601□-N	600	100 MHz,200 mV	0.1	2000
PBY201209T-102□-N	1000	100 MHz,200 mV	0.12	1500
PBY201209T-152□-N	1500	100 MHz,200 mV	0.3	1000

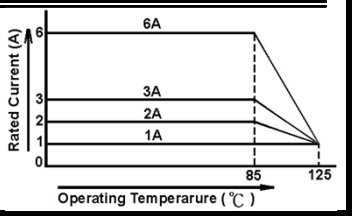
NOTE: □-tolerance Y=±25% / T=±30%

1.Operating temperature range －５５℃~１２５℃(Including self - temperature rise)

2.Rate Current : Applied the current to coils, the temperature rise shall not be more than 30℃

3.As for PB/UPB type. Rated Current is derated as right figure depending on the operating temprature

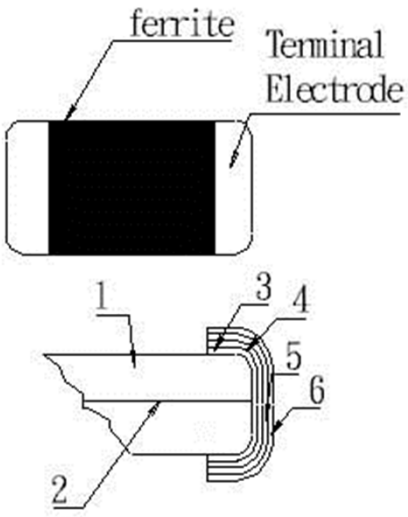
"-N" FOR COMPLETELY LEAD FREE TYPE(INCLUDING FERRITE BODY & SOLDER)



PBY201209T Series Specification

8 PBY201209T Series

8.1 Construction:



8.2 Material List:

No	Part	Material
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu ≧1.0um
5	Ni plating	Ni ≧1.0um
6	Sn plating	Sn ≧3.0um

PBY201209T Series Specification

9 Reliability Of Ferrite Multilayer Chip Bead

1-1.Mechanical Performance

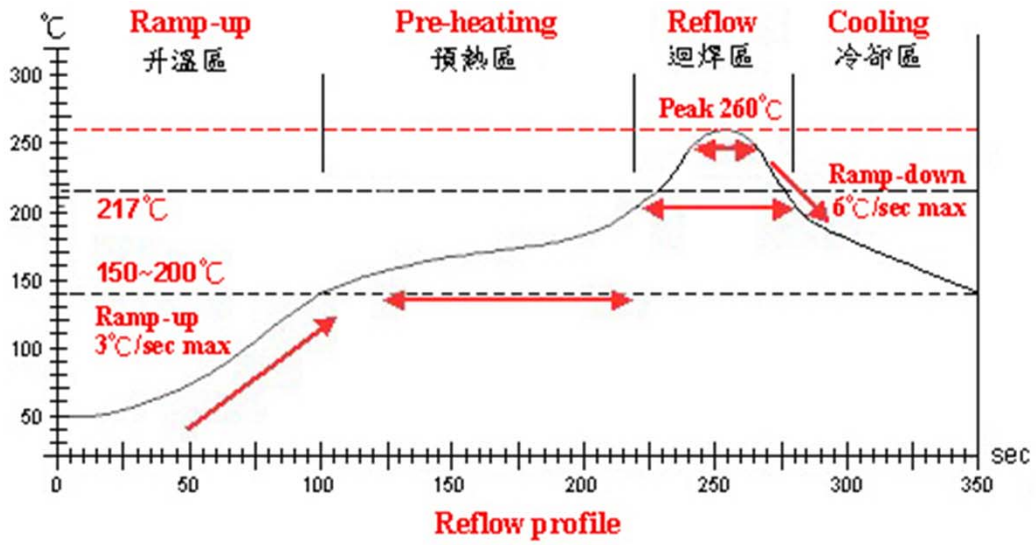
No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Impedance : within ±30% of initial value	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination Chip F Mounting Pad	Test device shall be soldered on the substrate, then apply a force in the direction of the arrow. Force : 5N Keeping Time: 10±1sec

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Impedance: within±30% of initial value	One cycle: Step / Temperature (℃) / Time (min) 1 / -55±3 / 30 2 / 25±2 / 3 3 / 125±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 125±3℃ / Relative Humidity: 0% Applied Current: Rated Current /Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -55±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

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PBY201209T Series Specification



Reflow profile

Lead-Free(LF) 標準溫度分析範圍 Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T.~150℃	150℃~200℃	217℃	260±5℃	Peak Temp.~150℃
標準時間 Time spec.	—	60~180 sec	60~150 sec	20~40 sec	—
實際時間 Time result	—	75~100 sec	90~120 sec	20~35 sec	—

NOTE :

1. Re-flow possible times : within 2 times
2. Nitrogen adopted is recommended while in re-flow

PBY201209T Series Specification

10 Product Test Data

Form No.: QF-1419
Edition: 2

Chilisin P/N: PBY201209T-601Y-N

Test Item (unit)	Z (Ω)	RDC (Ω)	A m/m	B m/m	C m/m	D m/m					
Customer Requirement	600±25%										
Spec Criteria		0.10Max.	2.0±0.2	1.25±0.2	0.9±0.2	0.5±0.3					
Test Condition	200mV 100MHz										
1	616	0.058	1.97	1.18	0.85	0.54					
2	565	0.058	1.94	1.2	0.87	0.58					
3	555	0.059	1.93	1.26	0.85	0.55					
4	583	0.06	1.94	1.21	0.87	0.53					
5	571	0.058	1.95	1.21	0.86	0.52					
6	608	0.059	1.95	1.19	0.84	0.51					
7	623	0.059	1.98	1.24	0.85	0.57					
8	615	0.06	1.97	1.22	0.85	0.54					
9	593	0.06	1.95	1.23	0.86	0.53					
10	559	0.059	1.98	1.24	0.87	0.51					
11											
12											
13											
14											
15											
$\overline{X}$	588.8	0.059	1.956	1.218	0.857	0.538					
R	68	0.002	0.05	0.08	0.03	0.07					
Customer Sample											

Test Instrument

HP4291A RF IMPEDANCE / MATERIAL ANALYZER FOR Z
CHEN HWA 502BC / HP4338B FOR RDC

Appearance and Dimensions:

Appearance: Visual inspection according to inspection criteria.
Dimension: Measured with slide calipers.

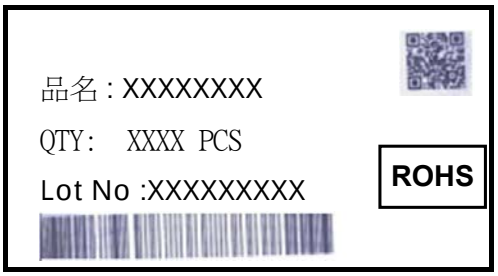
Test Conditions:

	Unless Otherwise Specified	In Case of Doubt
Temperature	Ordinary Temperature (15 to 35℃)	20 to 30℃
Humidity	Ordinary Humidity (25 to 85 %RH)	50 to 80 %RH

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包裝Label 之零件 Part number 說明:

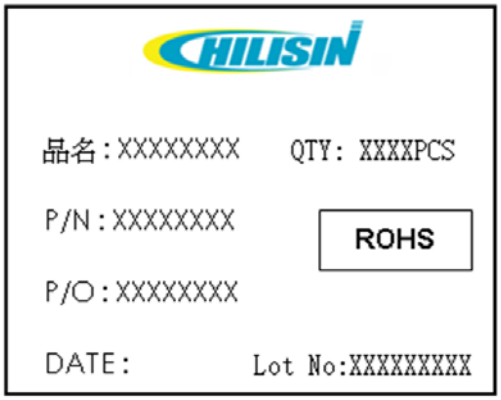
REEL



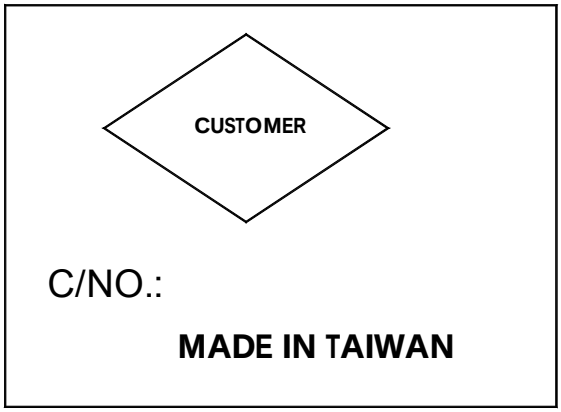
Box

條碼





Carton



Item :

P/N :

奇力新品名:

P/O :

QTY :

DATE :

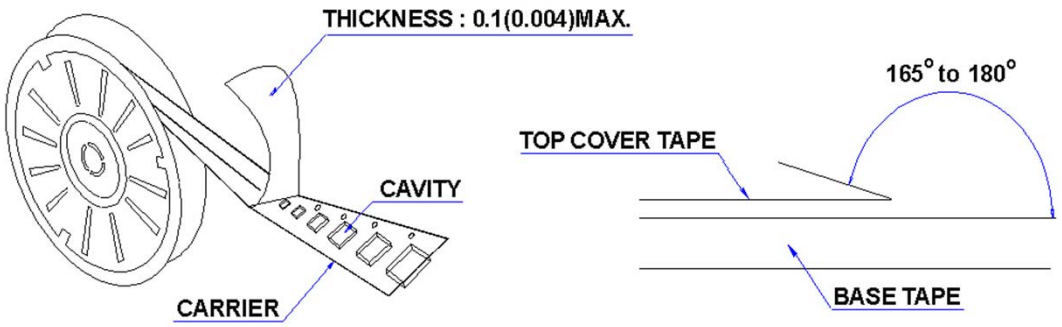
N.G : KG G.W: KG

PBY201209T Series Specification

11 Packaging:

11.1 Packaging -Cover Tape

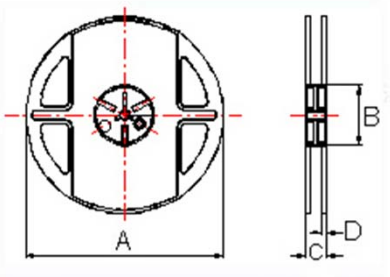
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	PCS/REEL
PB060303	15000
PB100505	10000
PB160808	4000
PB201209	4000

11.3 Reel Dimensions



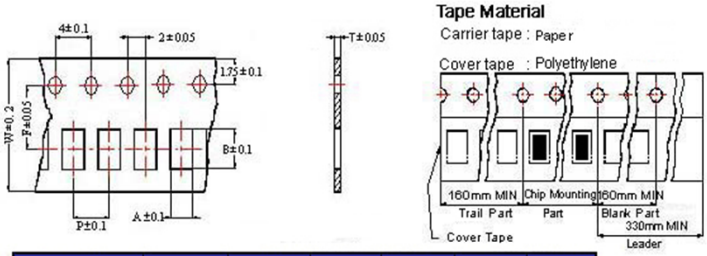
Dimensions in mm

TYPE	A	B	C	D
PB060303	178	60	12	1.5
PB100505	178	60	12	1.5
PB160808	178	60	12	1.5
PB201209	178	60	12	1.5

PBY201209T Series Specification

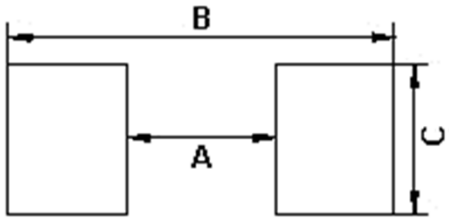
11 Packaging:

11.4 Tape Dimensions in mm



TYPE	A	B	T	W	P	F
PB060303	0.37	0.67	0.42	8	2	3.5
PB100505	0.62	1.12	0.60	8	2	3.5
PB160808	1.05	1.85	0.95	8	4	3.5
PB201209	1.50	2.30	0.97	8	4	3.5

12 Recommended Land Pattern:



Dimensions in mm

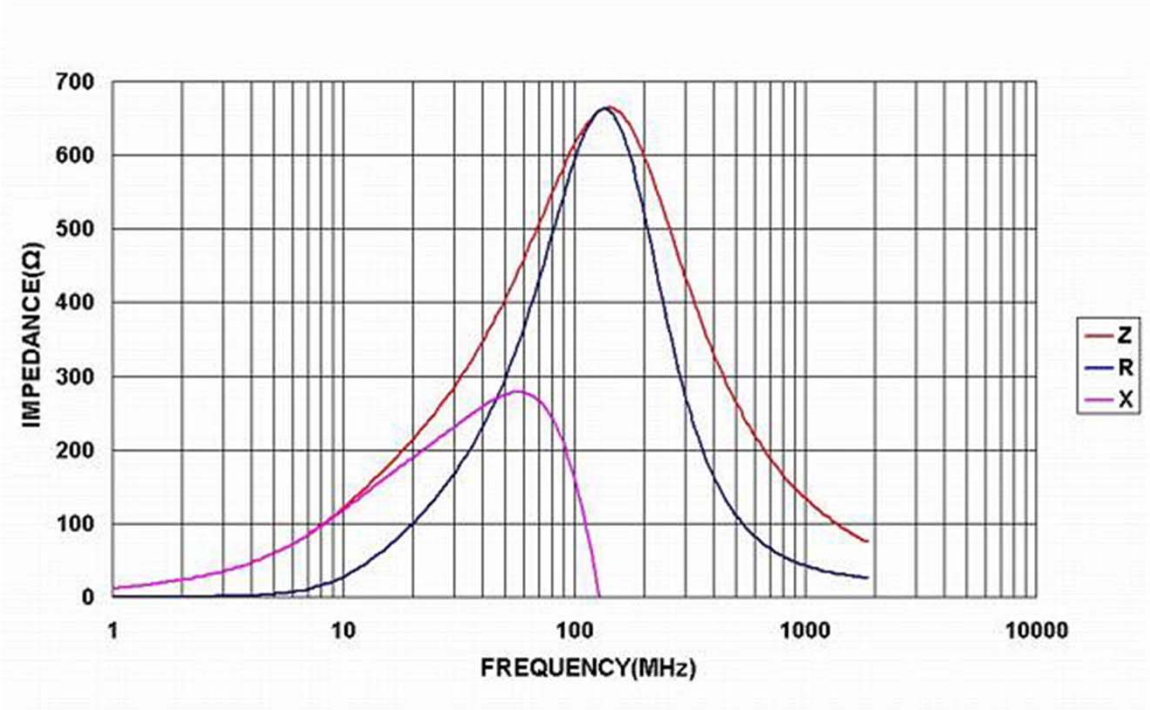
TYPE	A	B	C
PB201209	1.0 ~ 1.2	2.6 ~ 4.0	1.0 ~ 1.2

13 Note:

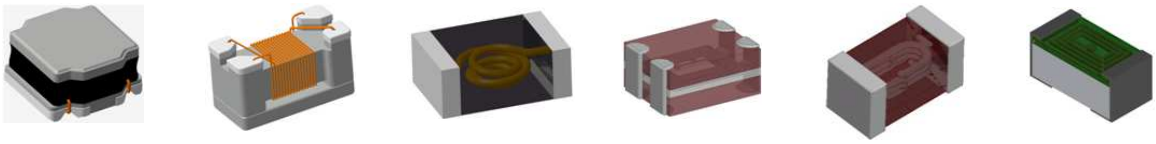
1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
2. Do not knock nor drop.
3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
5. The moisture sensitivity level (MSL) of products is classified as level 1.

PBY201209T Series Specification

14 Graph: PBY201209T-601Y-N



CHILISIN ELECTRONICS CORP



Chilisin
Stress Test Qualification Report

Chilisin PN: PBY201209T Series

Date: 2017/12/30

RA Lab. : 886-3-5992646#346

CHILISIN ELECTRONICS CORP

Stress Test Qualification Summary

Chilisin PN : PBY201209T Series **Date: 2017/12/30**

Stress	Test Conditions	Sample Size	Specification	Result
Temperature Cycling	Temperature (℃): -55℃~125℃ Cycle: 100	10	1. Electrical characterization change range 2. Appearance-No damage (OM)	Pass
Biased Humidity	Temperature (℃): 40±2℃ Humidity (%): 90~95% Time (Hours): 1000	10	1. Electrical characterization change range 2. Appearance-No damage (OM)	Pass
High Temperature Exposure (Storage)	Temperature (℃): 125±3℃ Applient Current : Rated Current Time (Hours): 1000	10	1. Electrical characterization change range 2. Appearance-No damage (OM)	Pass
Low Temperature Exposure (Storage)	Temperature (℃): -55±3℃ Time (Hours): 1000	10	1. Electrical characterization change range 2. Appearance-No damage (OM)	Pass
Vibration	Axial (X, Y, Z): 10 to 55 to 10Hz for 1min / Amplitude: 1.5mm Time (Hours): 2 hrs	10	The forces applied on the parts must not damage the terminal electrode and the ferrite.	Pass
Resistance to Soldering Heat	Peak temperature (℃): 260±5℃ Reflow times: 2 times	10	1. Electrical characterization change range 2. Appearance-No damage (OM)	Pass
Solderability	Solder temperature (℃): 245±5℃(Pb-Free) Immersion time (Sec): 4±1 s	10	The electrodes shall be at least 95% covered with new solder coating(10X magnification)	Pass
Board Flex	Bending (mm): 2mm Holding time (Sec): 30s	10	No crack	Pass
Terminal Strength (SMD)	Apply force (N/ Kg): 5N Apply time (Sec): 10±1 s	10	No crack or no part being sheared off from its pad	Pass
Checked by: Vic Chen		Reported by: ShiTing Gu		

CHILISIN ELECTRONICS CORP

Temperature Cycling

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: HP 4291A		Test date:	2017/12/30
Test Condition:	Temperature (℃): -55℃~125℃ Cycle: 100		
Measurement Condition: 100MHz/0.2V			
Specification	1. Electrical characterization change range 2. Appearance-No damage (OM)		

MEAS	Z(Ω)		Δ(%)	Electrical Characterization	Appearance
Item	Before	After			
Spec	600.0 ± 25%		within±30(%)	Judge	No damage
1	691.32	714.49	3.35%	PASS	PASS
2	690.92	718.16	3.94%	PASS	PASS
3	674.84	706.49	4.69%	PASS	PASS
4	670.09	685.88	2.36%	PASS	PASS
5	682.02	699.71	2.59%	PASS	PASS
6	692.57	698.71	0.89%	PASS	PASS
7	698.02	698.41	0.06%	PASS	PASS
8	673.58	700.96	4.06%	PASS	PASS
9	702.82	715.16	1.76%	PASS	PASS
10	693.94	704.32	1.50%	PASS	PASS
X	687.01	704.23	2.52%		
R	32.73	32.28	4.63%		
MAX	702.82	718.16	4.69%		
MIN	670.09	685.88	0.06%		

CHILISIN ELECTRONICS CORP

Biased Humidity

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: HP 4291A		Test date:	2017/12/30
Test Condition:	Temperature (℃): 40±2℃ Humidity (%): 90~95% Time (Hours): 1000		
Measurement Condition: 100MHz/0.2V			
Specification	1. Electrical characterization change range 2. Appearance-No damage (OM)		

MEAS	Z(Ω)		Δ(%)	Electrical Characterization	Appearance
Item	Before	After			
Spec	600.0 ± 25%		within±30(%)	Judge	No damage
1	614.09	625.83	1.91%	PASS	PASS
2	700.12	710.34	1.46%	PASS	PASS
3	655.95	663.15	1.10%	PASS	PASS
4	668.92	675.82	1.03%	PASS	PASS
5	665.02	677.71	1.91%	PASS	PASS
6	662.01	674.67	1.91%	PASS	PASS
7	666.58	667.53	0.14%	PASS	PASS
8	661.15	670.04	1.34%	PASS	PASS
9	662.68	675.93	2.00%	PASS	PASS
10	656.02	667.23	1.71%	PASS	PASS
X	661.25	670.83	1.45%		
R	86.03	84.51	1.86%		
MAX	700.12	710.34	2.00%		
MIN	614.09	625.83	0.14%		

CHILISIN ELECTRONICS CORP

High Temperature Exposure (Storage)

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: HP 4291A		Test date:	2017/12/30
Test Condition:	Temperature (℃): 125±3℃ Applient Current : Rated Current Time (Hours): 1000		
Measurement Condition: 100MHz/0.2V			
Specification	1. Electrical characterization change range 2. Appearance-No damage (OM)		

MEAS	Z(Ω)		Δ(%)	Electrical Characterization	Appearance
Item	Before	After			
Spec	600.0 ± 25%		within±30(%)	Judge	No damage
1	683.08	671.94	-1.63%	PASS	PASS
2	655.85	655.42	-0.07%	PASS	PASS
3	662.15	654.52	-1.15%	PASS	PASS
4	682.32	675.28	-1.03%	PASS	PASS
5	687.29	677.12	-1.48%	PASS	PASS
6	716.32	692.25	-3.36%	PASS	PASS
7	596.12	602.77	1.12%	PASS	PASS
8	665.98	640.88	-3.77%	PASS	PASS
9	569.68	578.16	1.49%	PASS	PASS
10	679.51	679.64	0.02%	PASS	PASS
X	659.83	652.80	-0.99%		
R	146.64	114.09	5.26%		
MAX	716.32	692.25	1.49%		
MIN	569.68	578.16	-3.77%		

CHILISIN ELECTRONICS CORP

Low Temperature Exposure (Storage)

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: HP 4291A		Test date:	2017/12/30
Test Condition:	Temperature (℃): -55±3℃ Time (Hours): 1000		
Measurement Condition: 100MHz/0.2V			
Specification	1. Electrical characterization change range 2. Appearance-No damage (OM)		

MEAS	Z(Ω)		Δ(%)	Electrical Characterization	Appearance
Item	Before	After			
Spec	600.0 ± 25%		within±30(%)	Judge	No damage
1	689.51	692.57	0.44%	PASS	PASS
2	643.74	658.89	2.35%	PASS	PASS
3	653.21	678.25	3.83%	PASS	PASS
4	524.65	575.08	9.61%	PASS	PASS
5	701.28	689.89	-1.62%	PASS	PASS
6	566.04	609.91	7.75%	PASS	PASS
7	675.68	673.12	-0.38%	PASS	PASS
8	634.31	665.22	4.87%	PASS	PASS
9	657.14	673.38	2.47%	PASS	PASS
10	648.38	670.35	3.39%	PASS	PASS
X	639.39	658.67	3.27%		
R	176.63	117.49	11.24%		
MAX	701.28	692.57	9.61%		
MIN	524.65	575.08	-1.62%		

CHILISIN ELECTRONICS CORP

Vibration

Part No. :	PBY201209T Series	ample size (pcs):	10
Test Instrument: VS-5060M		Test date:	2017/12/30
Test Condition:	Axial (X, Y, Z): 10 to 55 to 10Hz for 1min / Amplitude: 1.5mm Time (Hours): 2 hrs		
Measurement Condition: Temperature-Room temperature			
Specification	The forces applied on the parts must not damage the terminal electrode and the ferrite.		

MEAS	Appearance	Judge
Dimension	No Damage	
1	OK	PASS
2	OK	PASS
3	OK	PASS
4	OK	PASS
5	OK	PASS
6	OK	PASS
7	OK	PASS
8	OK	PASS
9	OK	PASS
10	OK	PASS

CHILISIN ELECTRONICS CORP

Resistance to Soldering Heat

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: HP 4291A/ Solder pot		Test date:	2017/12/30
Test Condition:	Peak temperature (℃): 260±5℃ Reflow times: 2 times		
Measurement Condition: 100MHz/0.2V			
Specification	1. Electrical characterization change range 2. Appearance-No damage (OM)		

MEAS	Z(Ω)		△(%)	Electrical Characterization	Appearance
Item	Before	After			
Spec	600.0 ± 25%		within±30(%)	Judge	No damage
1	609.09	609.66	0.09%	PASS	PASS
2	666.43	655.08	-1.70%	PASS	PASS
3	581.78	586.36	0.79%	PASS	PASS
4	643.32	626.92	-2.55%	PASS	PASS
5	619.49	598.17	-3.44%	PASS	PASS
6	646.17	627.43	-2.90%	PASS	PASS
7	655.14	633.06	-3.37%	PASS	PASS
8	511.42	528.04	3.25%	PASS	PASS
9	629.67	624.02	-0.90%	PASS	PASS
10	475.31	493.68	3.86%	PASS	PASS
X	603.78	598.24	-0.69%		
R	191.12	161.40	7.31%		
MAX	666.43	655.08	3.86%		
MIN	475.31	493.68	-3.44%		

CHILISIN ELECTRONICS CORP

Sorderability

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: Solder pot		Test date:	2017/12/30
Test Condition:	Solder temperature (℃): 245±5℃(Pb-Free) Immersion time (Sec): 4±1 s		
Measurement Condition: Temperature-Room temperature			
Specification	The electrodes shall be at least 95% covered with new solder coating(10X magnification)		

MEAS	Appearance	Judge
Dimension	>95% solder coating	
1	OK	PASS
2	OK	PASS
3	OK	PASS
4	OK	PASS
5	OK	PASS
6	OK	PASS
7	OK	PASS
8	OK	PASS
9	OK	PASS
10	OK	PASS

CHILISIN ELECTRONICS CORP

Board Flex

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: PB-7011		Test date:	2017/12/30
Test Condition:	Bending (mm): 2mm Holding time (Sec): 30s		
Measurement Condition: Temperature-Room temperature			
Specification	No crack		

MEAS	Appearance	Judge
Dimension	No crack	
1	OK	PASS
2	OK	PASS
3	OK	PASS
4	OK	PASS
5	OK	PASS
6	OK	PASS
7	OK	PASS
8	OK	PASS
9	OK	PASS
10	OK	PASS

CHILISIN ELECTRONICS CORP

Terminal Strength (SMD)

Part No. :	PBY201209T Series	Sample size (pcs):	10
Test Instrument: PB-7011		Test date:	2017/12/30
Test Condition:	Apply force (N/ Kg): 5N Apply time (Sec): 10±1 s		
Measurement Condition: Temperature-Room temperature			
Specification	No crack or no part being sheared off from its pad		

MEAS	Appearance		Judge
Dimension	No crack	No part being sheard off	
1	OK	OK	PASS
2	OK	OK	PASS
3	OK	OK	PASS
4	OK	OK	PASS
5	OK	OK	PASS
6	OK	OK	PASS
7	OK	OK	PASS
8	OK	OK	PASS
9	OK	OK	PASS
10	OK	OK	PASS

PBY201209T Series Specification

10 Product Test Data

Form No.: QF-1419
Edition: 2

Chilisin P/N: PBY201209T-601Y-N

Test Item (unit)	Z (Ω)	RDC (Ω)	A m/m	B m/m	C m/m	D m/m					
Customer Requirement	600±25%										
Spec Criteria		0.10Max.	2.0±0.2	1.25±0.2	0.9±0.2	0.5±0.3					
Test Condition	200mV 100MHz										
1	616	0.058	1.97	1.18	0.85	0.54					
2	565	0.058	1.94	1.2	0.87	0.58					
3	555	0.059	1.93	1.26	0.85	0.55					
4	583	0.06	1.94	1.21	0.87	0.53					
5	571	0.058	1.95	1.21	0.86	0.52					
6	608	0.059	1.95	1.19	0.84	0.51					
7	623	0.059	1.98	1.24	0.85	0.57					
8	615	0.06	1.97	1.22	0.85	0.54					
9	593	0.06	1.95	1.23	0.86	0.53					
10	559	0.059	1.98	1.24	0.87	0.51					
11											
12											
13											
14											
15											
$\overline{X}$	588.8	0.059	1.956	1.218	0.857	0.538					
R	68	0.002	0.05	0.08	0.03	0.07					
Customer Sample											

Test Instrument

HP4291A RF IMPEDANCE / MATERIAL ANALYZER FOR Z
CHEN HWA 502BC / HP4338B FOR RDC

Appearance and Dimensions:

Appearance: Visual inspection according to inspection criteria.
Dimension: Measured with slide calipers.

Test Conditions:

	Unless Otherwise Specified	In Case of Doubt
Temperature	Ordinary Temperature (15 to 35℃)	20 to 30℃
Humidity	Ordinary Humidity (25 to 85 %RH)	50 to 80 %RH

Qisda

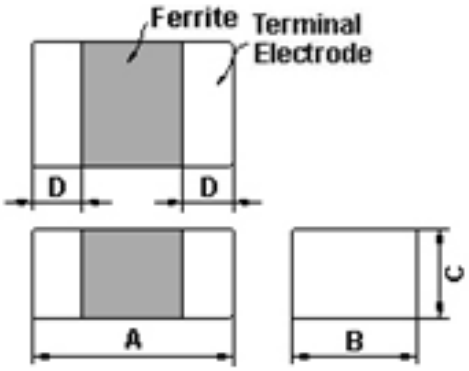
Component Test Report

(6H) 類零件檢驗表

廠商/ Maker:	CHILISIN	料號P/N:	6H.60160.0NE	Maker P/N	PBY201209T-601Y-N

項目/TEST ITEM	規格/SPEC.		TEST DATA					RESULT		備註/Remark
			NO.1	NO.2	NO.3	NO.4	NO.5	OK	NG	
1. 電感量(OA) Inductance	L( ) xxKHz xV									
	L( ) xxKHz xV									
2. 阻抗值	Z(Ω)100MHz, 200mV	600±25%	616	565	555	583	571	ˇ		
3. 直流電阻值 DCR Max.	RDC(Ω)	0.1Max	0.058	0.058	0.059	0.060	0.058	ˇ		
4. Solder ability	本體是否可在245±5℃/ 4±1s，達到95%的沾錫標準		OK	OK	OK	OK	OK	ˇ		
5. Resistance to Soldering Heat	260±5℃/10±1sec.		OK	OK	OK	OK	OK	ˇ		
6. Others	Vendor Type									

外觀尺寸圖/Appearance



*尺寸/Dimensions: (mm)

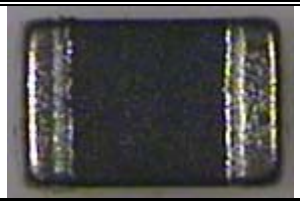
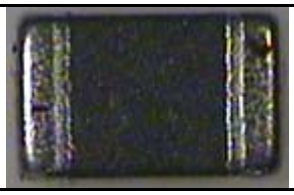
	Statement	Specification
A	2.00	±0.2
B	1.25	±0.2
C	0.90	±0.2
D	0.50	±0.2
E		
F		

Result	**Pass**
Prepare By Maker	Hebe.Lai
CE	**Zoey Wu**

*尺寸/Dimensions: (mm)

	SPEC	NO.1	NO.2	NO.3	NO.4	NO.5
A	2.00±0.2	1.97	1.94	1.93	1.94	1.95
B	1.25±0.2	1.18	1.20	1.26	2.21	1.21
C	0.90±0.2	0.85	0.87	0.85	0.87	0.86
D	0.50±0.2	0.54	0.58	0.55	0.53	0.52
E						
F						

Qisda

Step	Picture	Check Item
1		零件正面 標示 Making
2		零件背面
3		零件側面*4
4		

Qisda

Component Tear Down Report

No.	Inspect Items & Verify		Checking result			
	Items	Verify	Result	Remark	Prepare By Maker	Date
1	零件各部尺寸是否符合規格	OK	PASS		Hebe.Lai	2018.03.21
2	零件正面	OK	PASS		Hebe.Lai	2018.03.21
3	零件背面	OK	PASS		Hebe.Lai	2018.03.21
4	零件側面*4	OK	PASS		Hebe.Lai	2018.03.21
5	零件本體是否標示 Making，且符合規格	OK	PASS		Hebe.Lai	2018.03.21
6						

AP_GP BOM Report

Qisda P/N	6H.60160.0NE
Qisda Item description	#CHIP BEAD Z600 2A PBY201209T
Maker	CHILISIN
Maker P/N	PBY201209T-601Y-N
Create date	2024/07/29

Component type	Description	Supplier	Subpart type	Subpart Description	Subpart Supplier	Sample Description	Remark	Report No.	Test Date	Cd	Pb	Hg	Cr6+	PBBs/PBDEs	Br	Cl	Br+Cl	DIBP	DEHP	BBP	DBP	F	I	Exemptions
Inductors/Bead/Coils/Choke	Multilayer Ferrite Chip Bead SB/CL/PB/NB/GB/UPB/HP/VPB/HF/CP/MP SERIES	CHILISIN	Mixed all part-Inductor/Bead/Choke	Multilayer Ferrite Chip Bead SB/CL/PB/NB/GB/UPB/HP/VPB/HF/CP/MP SERIES	CHILISIN	Gunmetal electronic component (mixed all parts)	BEAD 泥測-2023	TWNC01202384	2023/08/25	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	
Summary data										N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	N.D	